

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10596387
<b>Filing Date:</b>	13-Apr-2007
<b>Title of Invention:</b>	EPOXY RESIN MOLDING MATERIAL FOR SEALING AND ELECTRONIC COMPONENT
<b>First Named Inventor/Applicant Name:</b>	Kazuyoshi Tendou
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<b>Attorney Docket Number:</b>	MIYOSH0006

Filed as Large Entity

### U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180